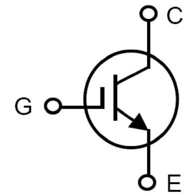
IXYS

1200V XPT™ GenX4™ IGBT

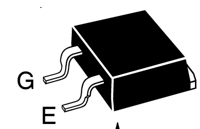
IXYA20N120B4HV
IXYP20N120B4

V_{CES} = 1200V
I_{C110} = 20A
$V_{CE(sat)}$ ≤ 2.1V
$t_{fi(typ)}$ = 90ns

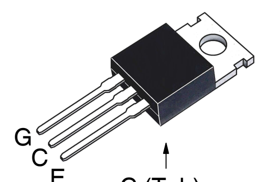
Extreme Light Punch Througnh
IGBT for up to 5 - 30kHz Switching



TO-263HV (IXYA..HV)



TO-220 (IXYP)



G = Gate D = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 175°C	1200	V
V_{CGR}	T_J = 25°C to 175°C, R_{GE} = 1MΩ	1200	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C	76	A
I_{C110}	T_C = 110°C	20	A
I_{CM}	T_C = 25°C, 1ms	130	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 150°C, R_G = 10Ω Clamped Inductive Load	I_{CM} = 40 $V_{CE} \leq$ 0.8 • V_{CES}	A
P_C	T_C = 25°C	375	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
M_d	Mounting Torque (TO-220)	1.13/10	Nm/lb.in
F_C	Mounting Force (TO-263HV)	10..65 / 22..14.6	N/lb
Weight	TO-263HV	2.5	g
	TO-220	3.0	g

Features

- Optimized for 5-30kHz Switching
- Positive Thermal Coefficient of Vce(sat)
- International Standard Packages

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250µA, V_{GE} = 0V	1200			V
$V_{GE(th)}$	I_C = 250µA, V_{CE} = V_{GE}	4.0		6.5	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			25	µA
	T_J = 150°C			5	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 20A, V_{GE} = 15V, Note 1		1.83	2.10	V
	T_J = 150°C		2.18		V

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 20A, V_{CE} = 10V, Note 1	7.5	12.5		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		890		pF
C_{oes}			58		pF
C_{res}			33		pF
$Q_{g(on)}$	I_C = 20A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		44		nC
Q_{ge}			8		nC
Q_{gc}			20		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		15		ns
t_{ri}	I_C = 20A, V_{GE} = 15V		47		ns
E_{on}	V_{CE} = 0.8 • V_{CES}, R_G = 10Ω		3.9		mJ
$t_{d(off)}$	Note 2		200		ns
t_{fi}			90		ns
E_{off}			1.6		mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		13		ns
t_{ri}	I_C = 20A, V_{GE} = 15V		35		ns
E_{on}	V_{CE} = 0.8 • V_{CES}, R_G = 10Ω		4.6		mJ
$t_{d(off)}$	Note 2		270		ns
t_{fi}			170		ns
E_{off}			2.7		mJ
R_{thJC}				0.40	°C/W
R_{thCS}	TO-220		0.50		°C/W

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

Fig. 1. Output Characteristics @ $T_J = 25^oC$

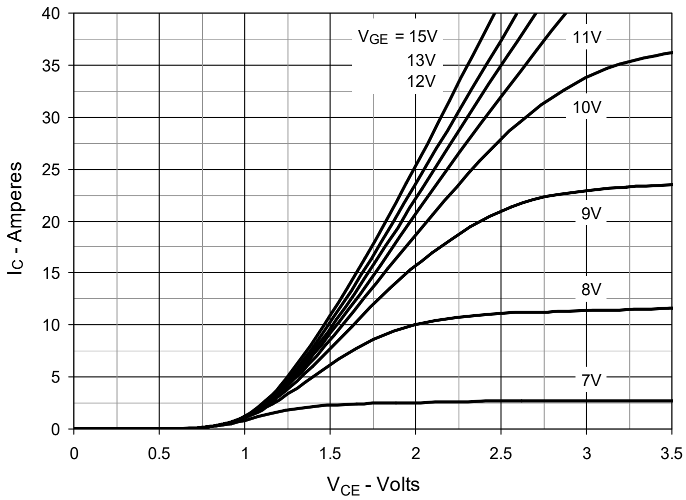


Fig. 2. Extended Output Characteristics @ $T_J = 25^oC$

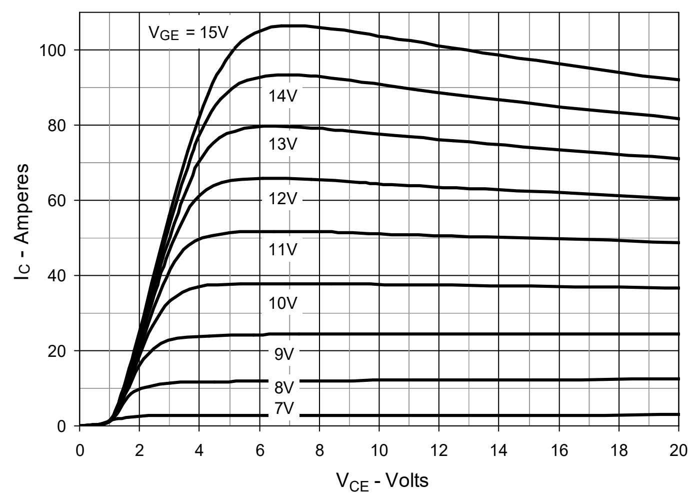


Fig. 3. Output Characteristics @ $T_J = 150^oC$

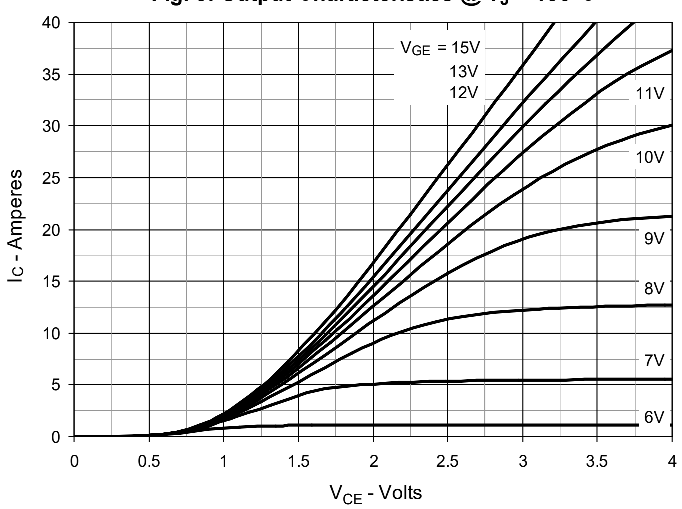


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

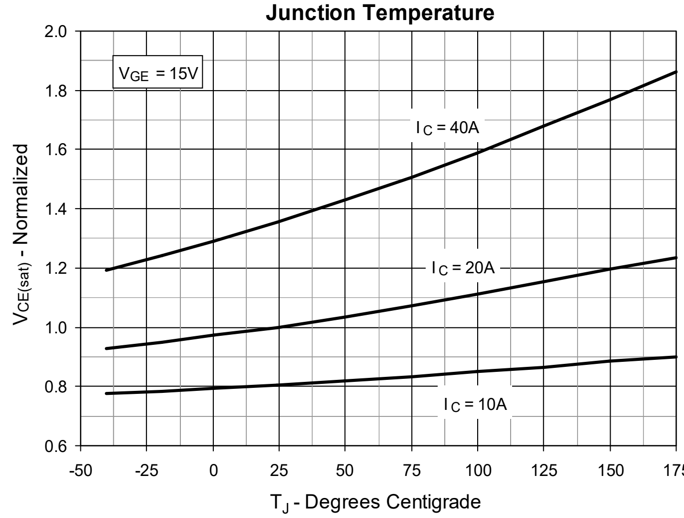


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

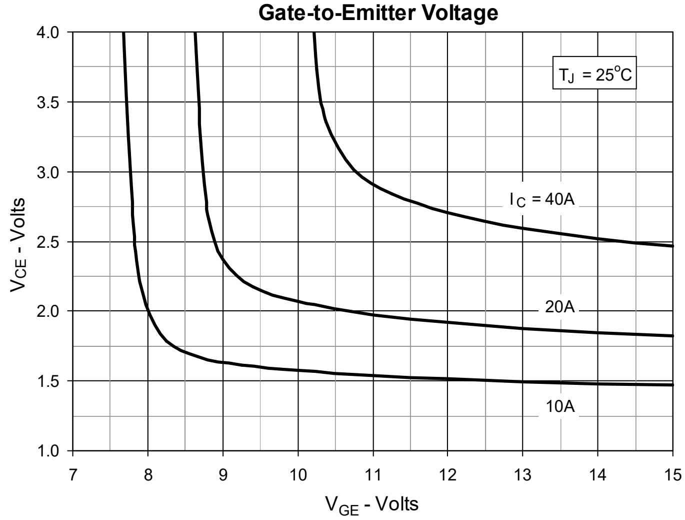


Fig. 6. Input Admittance

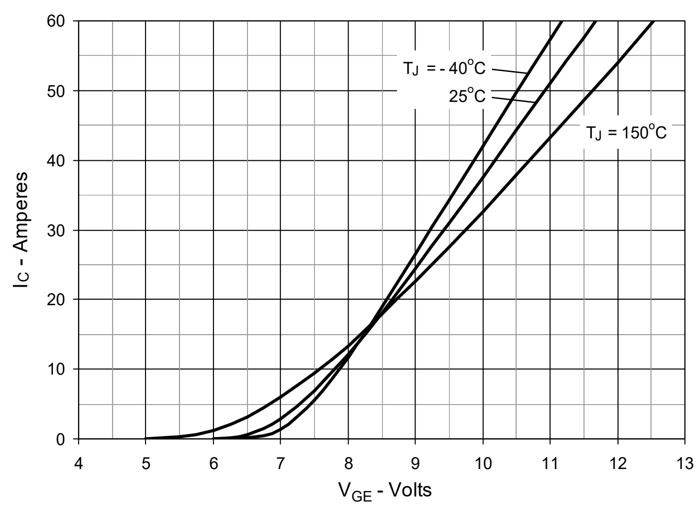


Fig. 7. Transconductance

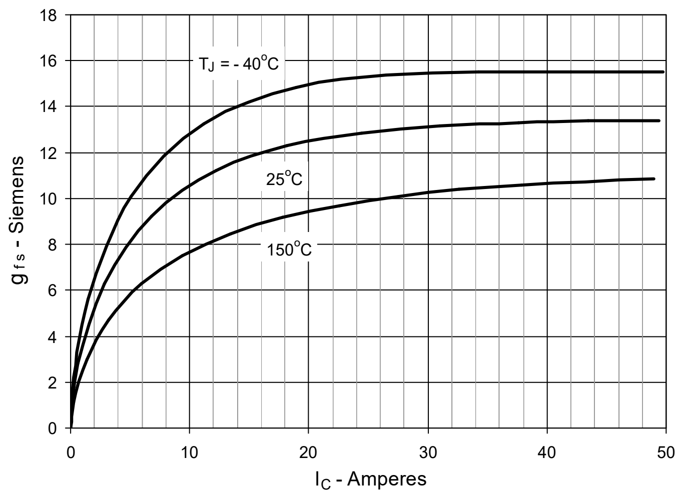


Fig. 8. Gate Charge

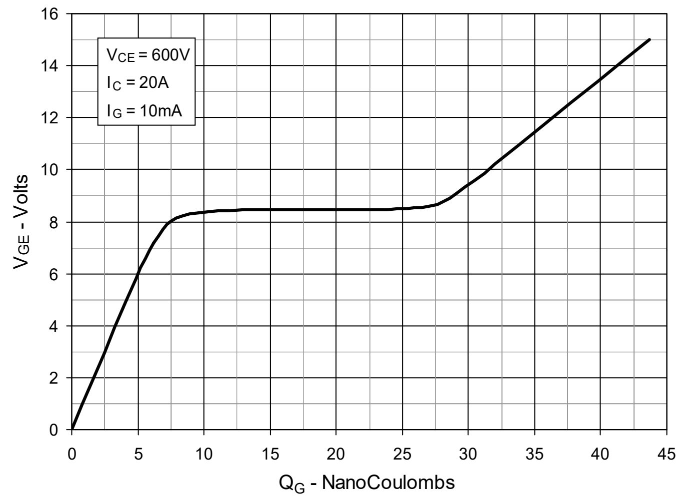


Fig. 9. Capacitance

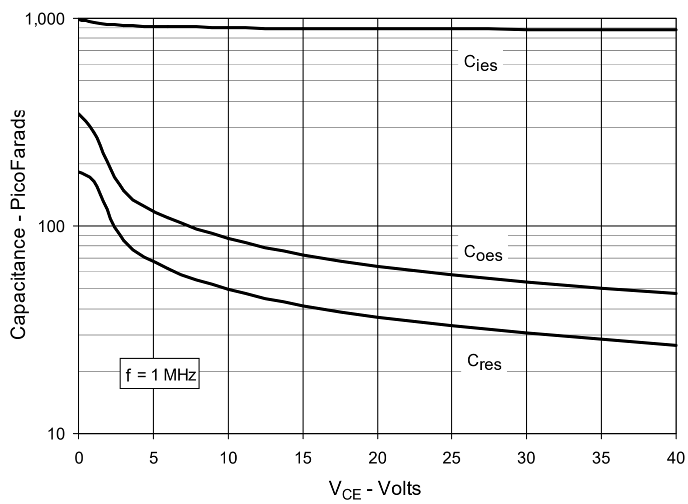


Fig. 10. Reverse-Bias Safe Operating Area

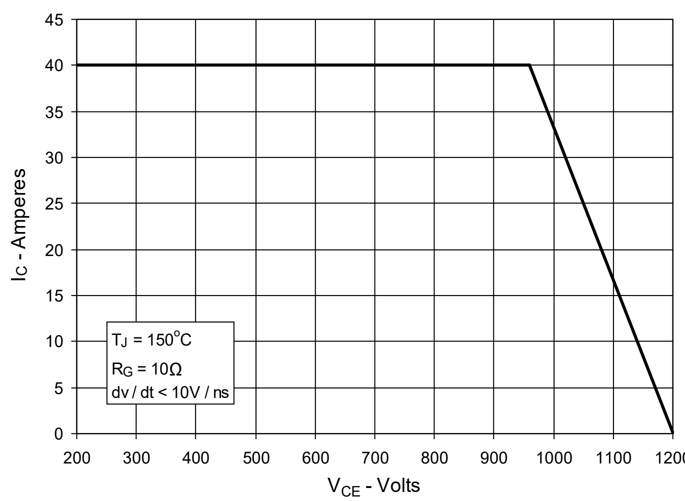


Fig. 11. Maximum Transient Thermal Impedance

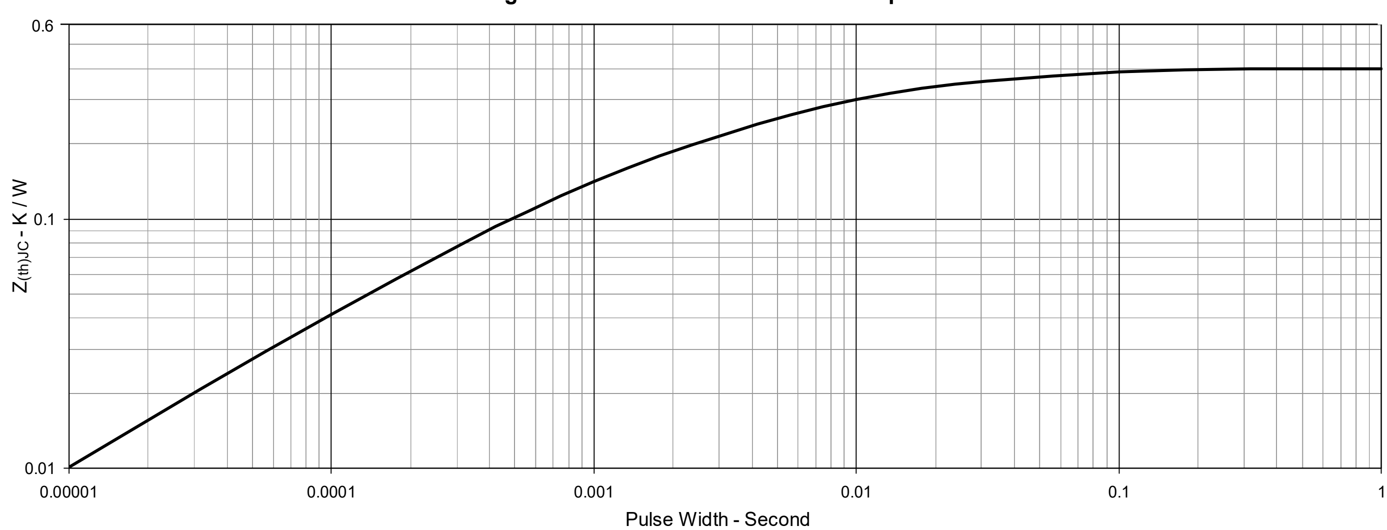


Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

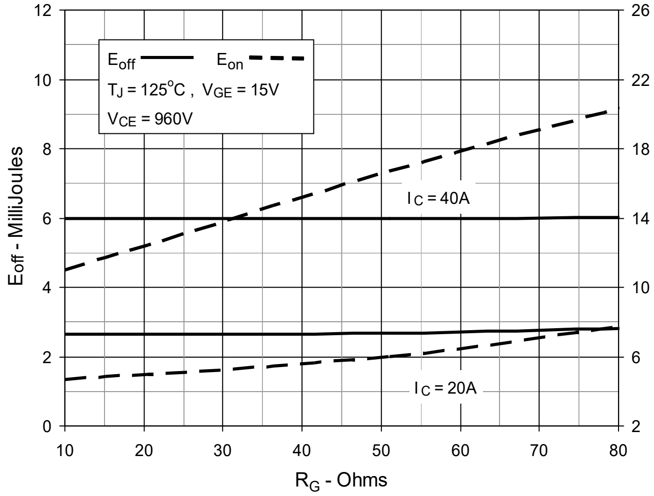


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

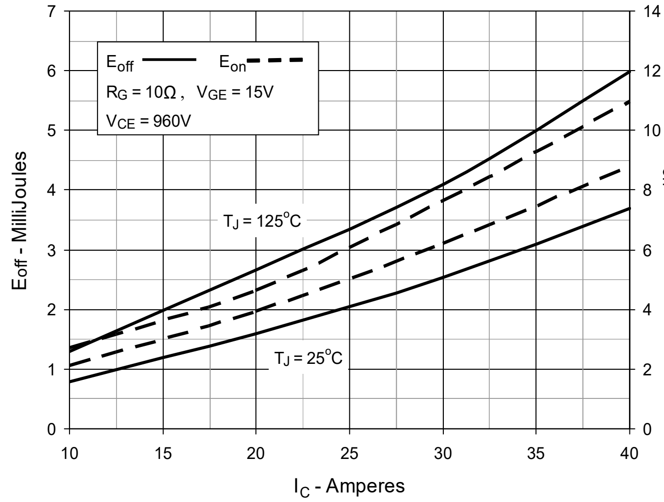


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

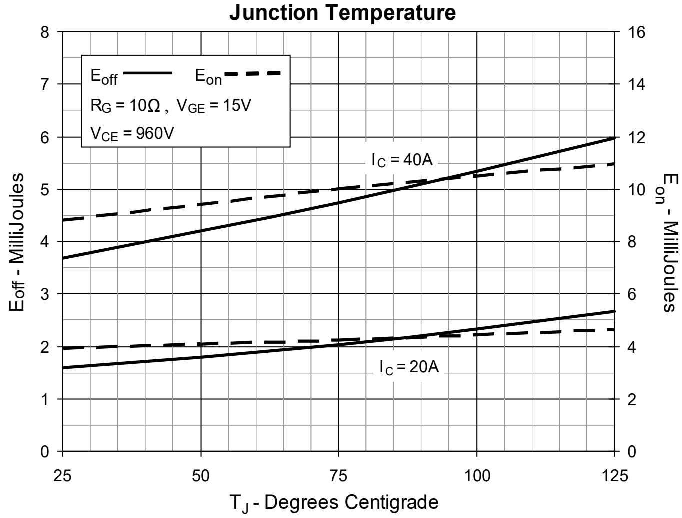


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

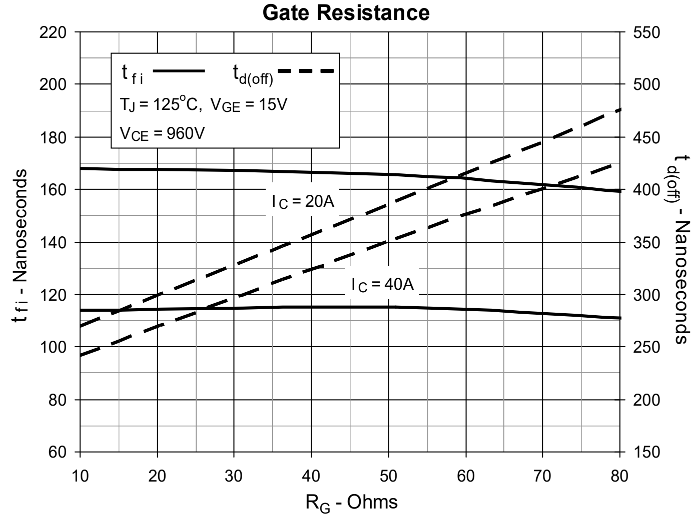


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

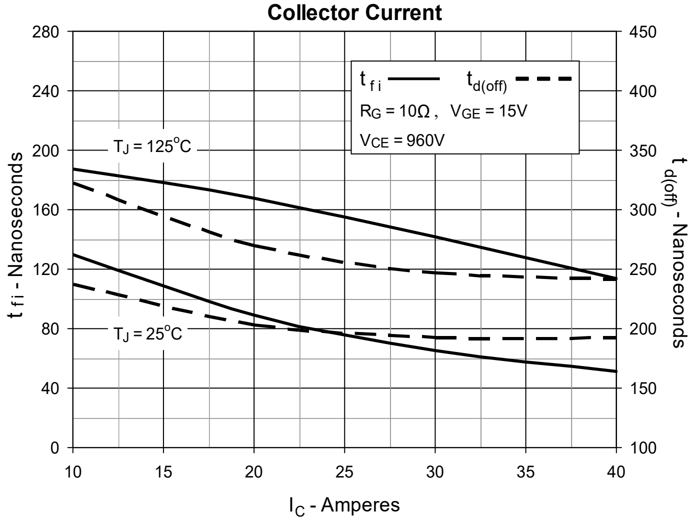


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

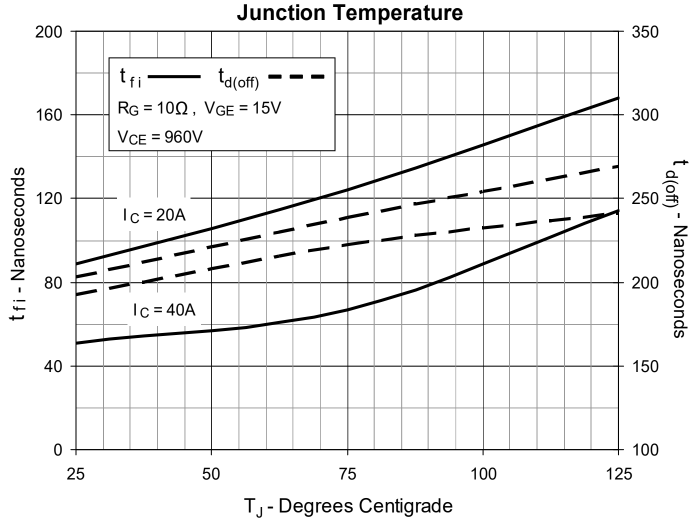


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

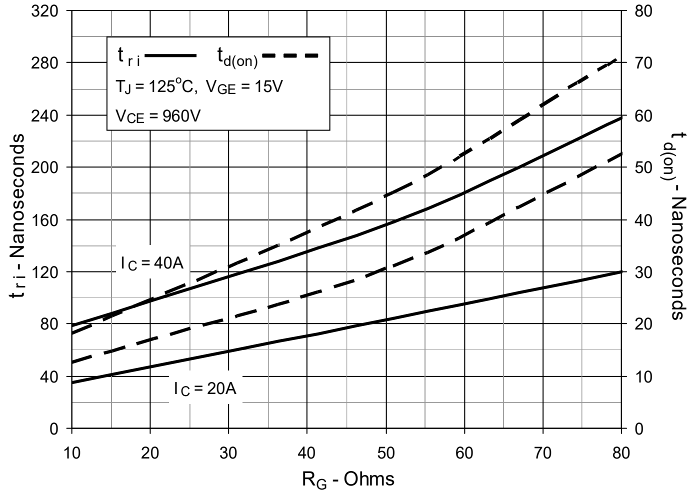


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

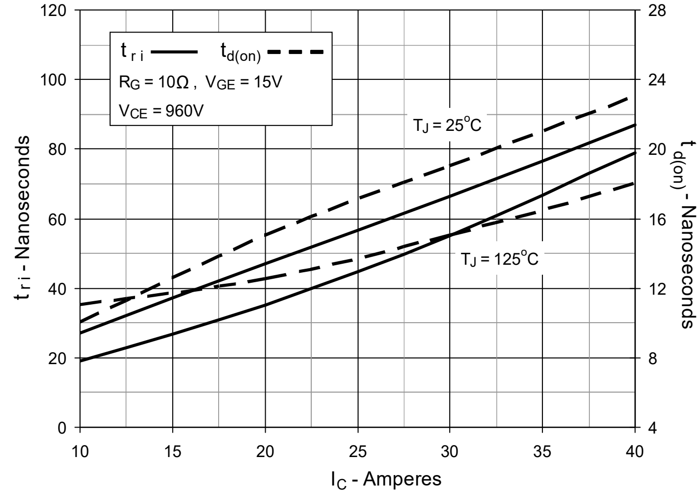
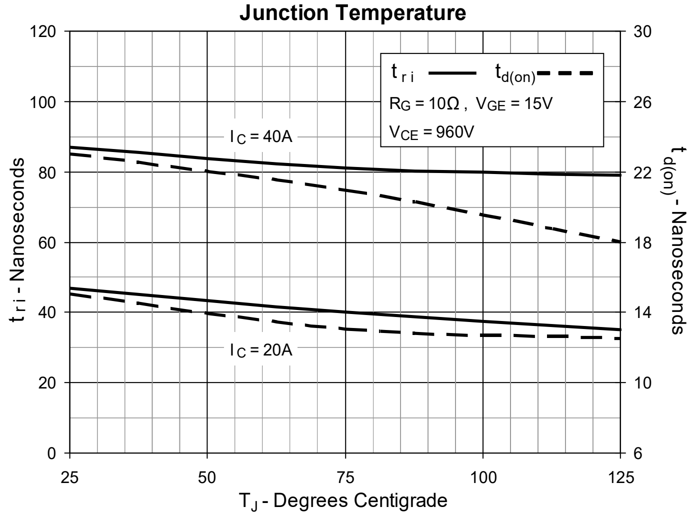
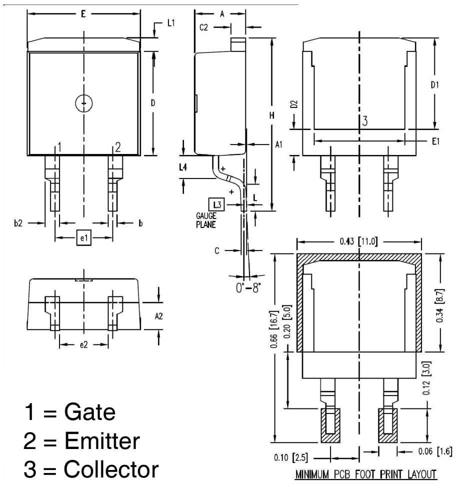


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



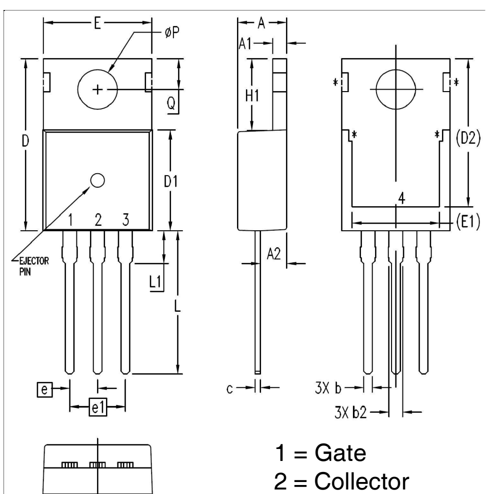
TO-263HV Outline



1 = Gate
2 = Emitter
3 = Collector

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.054	1.18	1.38
C	.018	.024	0.45	0.60
C2	.049	.055	1.25	1.40
D	.354	.370	9.00	9.40
D1	.311	.327	7.90	8.30
D2	.083	.098	2.10	2.50
E	.386	.402	9.80	10.20
E1	.307	.323	7.80	8.20
e1	.200 BSC		5.08 BSC	
(e2)	.163	.174	4.13	4.43
H	.591	.614	15.00	15.60
L	.079	.102	2.00	2.60
L1	.039	.055	1.00	1.40
L3	.010 BSC		0.254 BSC	
(L4)	.071	.087	1.80	2.20

TO-220 Outline



1 = Gate
2 = Collector
3 = Emitter

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100 BSC		2.54 BSC	
e1	.200 BSC		5.08 BSC	
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
ØP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20